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**Kim**

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(54) **DOUBLE FLOOR PLATE MATERIAL  
STRUCTURE AND METHOD FOR FORMING  
THE SAME**

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(2013.01); **Y10T 29/49828** (2015.01)

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(56) **References Cited**

**U.S. PATENT DOCUMENTS**

7,490,439 B2 \* 2/2009 Teramura ..... E04F 15/02452  
52/126.6

**FOREIGN PATENT DOCUMENTS**

JP 10-115077 A 5/1998  
JP 3119254 U 2/2006  
KR 2002-99579 Y1 12/2002  
KR 10-2012-0027921 A 3/2012

\* cited by examiner

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(57) **ABSTRACT**

Disclosed are a raised access floor panel material structure disposed on a floor of a structure, wherein a floor panel material of floor material capable of easily accommodating wires for power, computer and communication or devices such as air conditioning facilities etc. at its lower part is formed in an assembled manner by a floor consisting of combined unit panels and is conveniently laid on the a floor surface to form a neat floor panel and a method for forming the raised floor panel material structure.

**3 Claims, 9 Drawing Sheets**